

CLAIM AMENDMENTS

2. (Currently Amended) An epoxy resin composition that seals a semiconductor chip, said epoxy resin composition including an epoxy resin and a filler that fills said epoxy resin, wherein said filler contains ~~from~~ not less than 10 to ~~wt% and less than 15~~ wt%, with respect to total filler, of a filler component having an average particle size of no more than 10 μm .

3. (Previously Amended) The semiconductor device according to claim 6, wherein a color difference between color of a laser mark on a surface of said package and color of the surface of said package where the laser mark is not present, as measured by a colorimeter, has a value of at least 10.

4. (Previously Amended) The semiconductor device according to claim 6, wherein said package includes a dye providing the color of the surface of said package.

6. (Currently Amended) A semiconductor device including:
a semiconductor chip;
a package of an epoxy resin encapsulating said semiconductor chip; and
a filler that fills said epoxy resin, wherein said filler contains ~~from~~ not less than 10 ~~to~~ wt% and less than 15 wt%, with respect to total filler of a filler component having an average particle size of no more than 10 μm .